

INFORMATION DISCLOSURE CITATION
(Use several sheets if necessary)

Docket Number (Optional)

BU9-98-110

Application Number

09/298,786

Applicant(s)

Armbrust et al

Filing Date

04/23/99

Group Art Unit

2813

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	IF APPLICABLE RELEVANT PROPRIETARY
DNL		5,447,887	09/05/95	Filipiak et al.			1
DNL		5,633,047	05/1997	Brady et al.	427	437	
DNL		4,505,029	03/1985	Owyang et al.	427	89	
DNL		5,833,758	04/1997	Linn et al.	134	1.2	
bHL		5,503,704	04/1996	Bower et al.	427	399	
DNL		6,046,101	04/2000	Dass et al.	438	791	
DNL		5,844,317	12/1998	Bertolet et al.	257	773	

FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO

OTHER DOCUMENTS *(Including Author, Title, Date, Pertinent Pages, Etc.)*

DNL IBM Technical Disclosure, Cronin et al., "Copper/Polyimide Structure with Selective Cu3Si/SiO₂ Etch Stop," Vol. 37, No. 06A June 1994, p.53.

EXAMINER

Donghee Kang

DATE CONSIDERED

12-21-00

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.